



Attachment 2: Clean s t of claims as am nded

1. A method for packaging a microelectromechanical system (MEMS) device comprising:
using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;
providing a cavity having a smooth surface perimeter and extending through the release sheet
and at least partially through the MEMS package flexible layer;
removing the release sheet; and
attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the
MEMS device being positioned within the cavity.

2. The method of claim 1 further comprising providing MEMS vias through the MEMS package
flexible layer and the cover extending to connection pads of the MEMS device and applying a MEMS
pattern of electrical conductors over the MEMS package flexible layer and the cover and extending
through the MEMS vias to the connection pads.

3. The method of claim 1 wherein using the adhesive to attach the release sheet to the MEMS
package flexible layer comprises coating the MEMS package flexible layer with the adhesive, partially
curing the adhesive, and then attaching the release sheet.

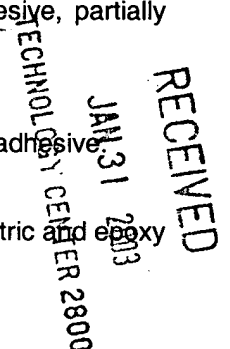
4. The method of claim 3 wherein attaching the MEMS device comprises using the adhesive

6. The method of claim 1, wherein the adhesive comprises a mixture of photodielectric and epoxy
materials.

7. A method for packaging a microelectromechanical system (MEMS) device comprising:
using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;
providing a cavity extending through the release sheet and partially through the MEMS package
flexible layer;
providing a protective coating in the cavity;
then removing the release sheet; and
attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the
MEMS device being positioned within the cavity.

8. The method of claim 7 wherein the protective coating comprises a hermetic seal on the MEMS
package flexible layer.

16. A method for packaging a microelectromechanical system (MEMS) device comprising:
coating an MEMS package flexible layer with an adhesive;



partially curing the adhesive;
using the adhesive to attach a release sheet to the MEMS package flexible layer;
providing a cavity having a smooth surface perimeter and extending through the release sheet, the adhesive, and at least partially through the MEMS package flexible layer;
removing the release sheet;
using the adhesive to attach the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity;
providing MEMS vias through the MEMS package flexible layer extending to connection pads of the MEMS device; and
applying a MEMS pattern of electrical conductors on the MEMS package flexible layer and extending through the MEMS vias to the connection pads.

19. The method of claim 16 wherein providing the cavity comprises providing a cavity extending partially through the MEMS package flexible layer and further comprising, prior to removing the release sheet, providing a hermetic coating in the cavity.